

April 12, 2004

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile      Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

**Continuation of**

Serial No.: 09/970,787 10/5/01

LAIN-JONG LI, TIEN-I BAO, SHWANG-MING JENG,  
SYUN-MING JANG, JUN-LUNG HUANG, JEN - CHENG  
LIU

COMPOSITE ETCHING STOP IN SEMICONDUCTOR  
PROCESS INTEGRATION

**PRELIMINARY AMENDMENT**

Dear Sir:

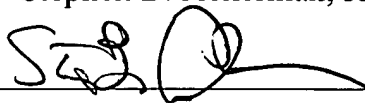
This is a preliminary amendment for the above referenced ~~Continuation~~ Patent  
Application. Please amend the above identified application for patent as follows:

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States  
Postal Service as first class mail in an envelope addressed to: Commissioner of Patents  
and Trademarks, Washington, D.C. 20231, on April 13, 2004.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date



4/13/04

March 23, 2004

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/970,787 10/05/2001

L.J.LI ET AL

"COMPOSITE ETCHING STOP IN  
SEMICONDUCTOR PROCESS INTEGRATION"

PRELIMINARY AMENDMENT


Dear Sir:

Please enter a preliminary amendment for the divisional of the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on April 13, 2004.

Stephen B. Ackerman, Reg. No. 37,761

Signature   
Date April 13, 2004

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 8 of this paper.